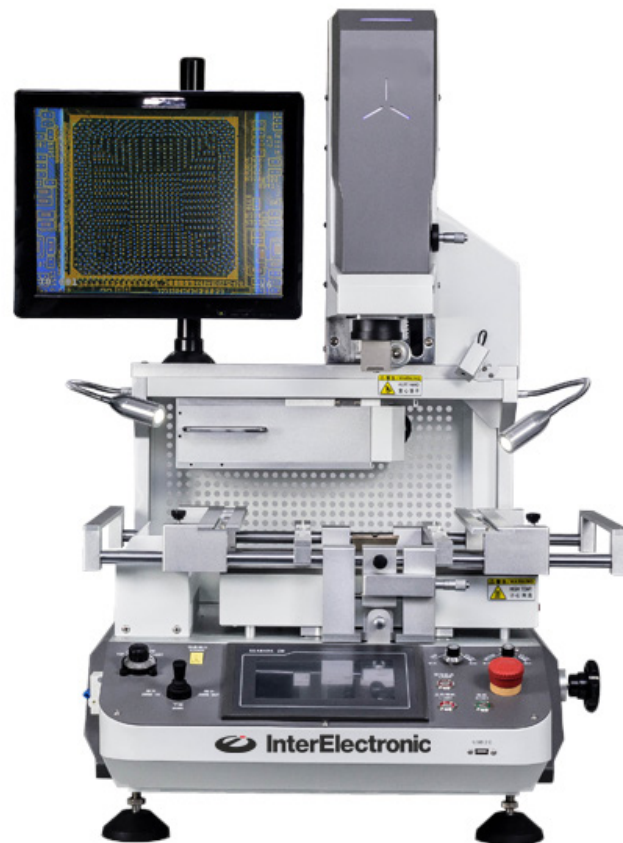


BGA REWORK STATIONS

INTEON



INTRODUCTION



INTEON BGA rework systems allows attractive price and high quality performance for lead free process. INTEON BGA rework systems assure an optimum of process stability by innovative technology. All the electrical system totally match the European quality standard and other international safety standard. We are offering different models to find the best solution for your production even you are manufacturing OEM or small repair service.

WARRANTY

Best in the industry warranty – 2 years full warranty.

SUPPORT

For more complex appliances our company offers a well-needed training for set up and usage. We grant the repair of all of the products traded by our company during and after the warranty period. As well as we guarantee the continuous supply of accessories.

ON-SITE VISIT

In case if any of our products aroused your interest INTEON would be glad to visit your company and hold a presentation of the product of your interest. Major machines also could be observed at our partners' site.

OFFERS

Most of the prices of our products can be requested on our website and will be sent via email to you. In case of special and more complex machines the prices are given after consultation individually through a price offer. If you are interested in more information or user manuals of our products we recommend you to visit our website (www.inte-on.com), which is updated continuously with professional information. We also recommend you to visit our office, where you can purchase any of the needed devices and spare parts of the product of your interest.

BGA REWORKS

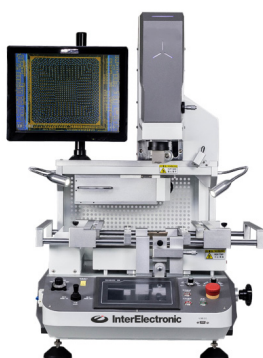
IE 5800BGA



Economic type rework station

p. 6-7

IE 6200BGA



Rework station with optical positioning

p. 8-9

IE 6200BGA/LED



Rework station with HD optical positioning

p. 10-11

IE 6800BGA

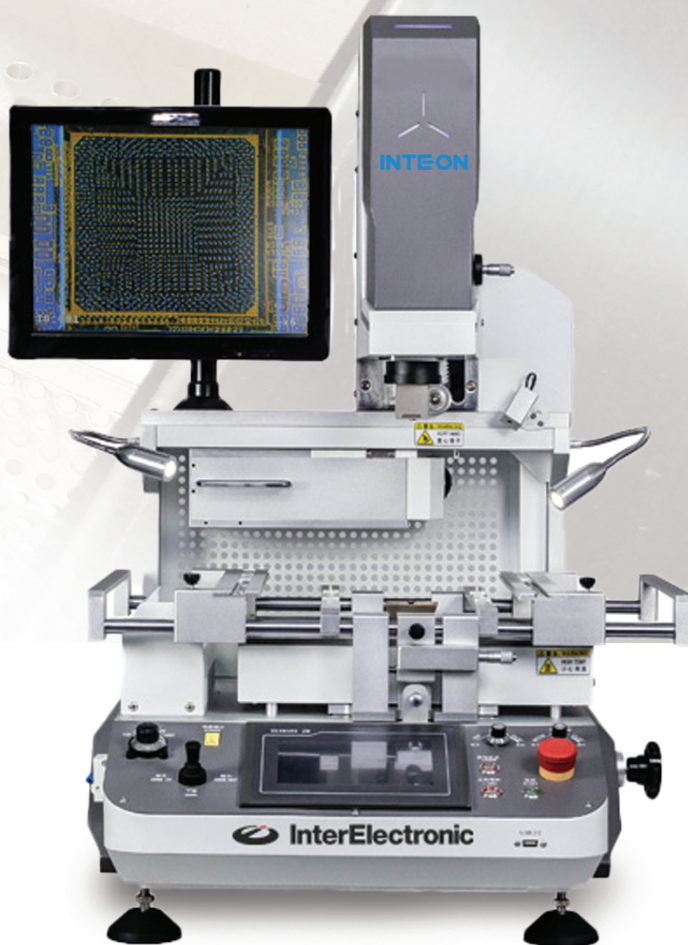
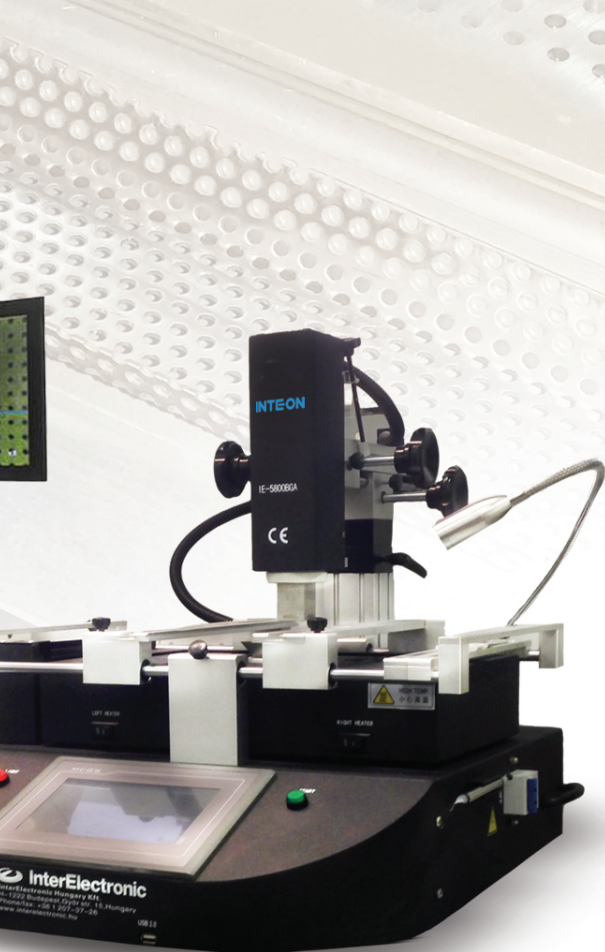


Automatic rework station with optical positioning
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INTEON

2 YEAR FULL WARRANTY





BGA REWORK STATION

IE-5800BGA

- High definition touch screen, PLC control
- High positioning accuracy and fast maneuverability
- 3 independent heating areas



FEATURES

Adopt liner slide

Which makes X,Y,Z axis all can do precision adjustment or fast positioning, with high positioning accuracy and fast maneuverability.

High definition touch screen

PLC control, can save multiple groups profile, password protection and modify function, and can save multiple groups profile, equipped with instant temperature curve analysis function.

3 independent heating areas

There are from top to bottom. The 1st and 2nd are hotair heaters, the 3rd is IR preheating, temperature controlled within $\pm 3^{\circ}$. Top heater can be adjusted freely. Top and bottom temperature can control many groups and sections of temperature parameters at the same time. The third IR heater can be adjusted the power consumption.

Easy to install and change

Offer all kinds of hot-air nozzle, it can rotate 360° . With magnet, easy to install and change, customized is available. Bottom IR heater ensure an even heat for PCB board.

High-precision K-type thermocouple

Choose imported high-precision K-type thermocouple, closed loop control and automatic temperature compensation system, combined PLC module for the precision control of temperature.

IE-5800BGA

Flexible fixture for PCB positioning

Use a V-groove equipped with a flexible fixture for PCB positioning to protect the PCB from deformation when heated or cooled, and it can rework for any BGA package size. Powerful cross-flow fan rapidly cool the PCB board to improve efficiency, also built-in vacuum pump and external vacuum suction pen, pick up the chips rapidly. After finishing disordering & soldering, there is an alarming.

Automatic power-off protection device

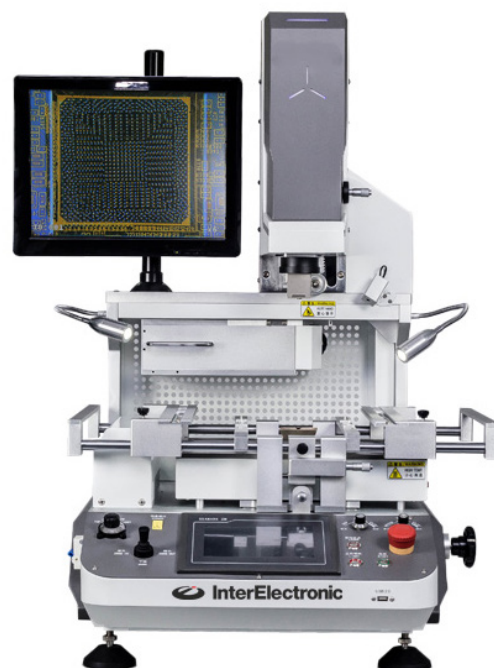
CE certificate, with emergency stop and Automatic power-off protection device when abnormal accident happens, with a double over-heating protection control.

Model	IE-5800BGA Specifications
Total Power	4500W
Power	AC 220 V $\pm 10\%$ 50/60 Hz
Top heater power	800W
Bottom heater power	2nd heater 1200W, 3rd IR heater 2400W
Power supply	AC230V $\pm 10\%$ 50/60Hz
Dimension	L535*W650*H600mm
Positioning	V-groove, PCB support can be adjusted in any direction with external universal fixture
Temperature control	(K Sensor) closed loop, independent heating, precision within $\pm 3^\circ$
PCB size	Max 350*330mm Min 20*20 mm
Electrical selection	Highly sensitive temperature control module, Touch screen
Weight	34kg
Package	Wooden Box
G.W.	51KG
Package dimension	L71*W71*H68cm

BGA REWORK STATION

IE-6200BGA

- Stable and Uniform Hot Air Heating System
- Emergency Stop Function
- Lower Heater Adjustable
- Carbon Fiber Infrared Pre-heater
- High-Precision PID Temperature Control System
- Industrial High-Definition CCD Camera(1.3MP)
- High-Precision Optical Alignment System
- High-Resolution Touch Screen HMI Interface
- Automatic Placement, Desoldering
- Built-In Pressure Sensor System To Protects The PCB
- Real-Time Temperature Monitoring and Over-Temperature Protection.
- Add a side camera, more clearly observe the rework process(Optional)



FEATURES

Superior safety functions

After finish desoldering and soldering, there is alarming, when temperature goes out of control, the circuit will automatically power off, it is of double excess temperature protection function. Temperature parameter has a password to avoid arbitrary changes, with superior safe protection functions, can protect PCB, components and the machine from damage at any abnormal situation.

Precise optical alignment system

With optical alignment system and clear images, components can enlarge up to Maximum 230 times, mounting accuracy within $\pm 0.01\text{mm}$, with a beam split, zoom in, zoom out and micro-adjust functions, adopted 12" HD monitor.

3 independent heating system

IE-6200BGA is available heating portion of the PCB board by hot-air circulate both from top and bottom at the same time. With large IR bottom heating, it can completely avoid PCB deformation during reworking period, you can use software to choose freely or use top heater or bottom heater departly and combine freely with top and bottom heater's capacity, to make it easies for rework double BGA, CCGA, QFN, CSP, LGA, SMD etc. External sensor socket is precise detected temperature to analyze and proof on actual temperature curve of BGA at the same time.

IE-6200BGA

Multi-function operation system

With touch screen interface, k-type thermocouple, close-loop control and Intelligent temperature compensation with automatically system, integrated design of top heater and sucker point. It can auto identify a high degree of suction and

mounting with automatic soldering and de-soldering functions. The temperature can be set to 8 segment and 8 segment constant temperature control, N groups of storage temperature setting parameters according to kinds of BGA chip set.

Model	IE-6200BGA Specification
Operation Mode	Automatic / Optical /Touch Panel
Voltage/Power	AC220V±10%(110V Optional), 50/60HZ / Top: 1200W, Bottom: 1200W, IR: 2700W
Heating Mode	Top/Bottom Nozzle Hot Air, Bottom Plates Infrared
Temperature Precision	2~3°C (1 Sensor Port)
Preheat Zone	280×380mm
Optical Alignment Precision	0.01MM
CCD Magnification:	5X~50X
LCD Display	15"720P HD LCD Display
For PCB Size/Chip Size	PCB Size: 415*370~22*22MM / Chip Size: 2*2MM ~ 50*50MM
Machine Dimension	L640*W630*H900 (MM)
Net Weight	79KG
Standard Wooden Packing	Packing Size: L750*W700*H950(MM) / G.W: 120KG

BGA REWORK STATION

IE-6200BGA/LED

- Stable and Uniform Hot Air Heating System
- Emergency Stop Function
- Lower Heater Adjustable
- Carbon Fiber Infrared Pre-heater
- High-Precision PID Temperature Control System
- SMD Feeding Device Support (Optional)
- High-Resolution Touch Screen HMI Interface
- Automatic Placement, Desoldering
- Built-In Pressure Testing Device to Protects the PCB
- Real-Time Temperature Monitoring and Over-Temperature Protection.
- Add a side camera, more clearly observe the rework process(Optional)
- High-Precision Optical Alignment System with Industrial High-Definition CCD (2MP)



FEATURES

Suitable for LED lamp beads repairing, size of micro LED components not less than 0.6*0.6mm can be repaired.

Suitable for LED lamp beads of tape packaging and bulk materials. Also any BGA and components which are difficult to repair.

High solution optical alignment system, accurate LED components positioning, ensure precise mounting.

Optical alignment is controlled electrically and rotate automatically.

Mounting head built-in pressure testing device to protect the PCB.

Built-in infrared laser positioning, fast positioning for PCB.

Adopt HIWIN precision guide rail for up and down movement system, ensure reliable and accurate running.

Adopt up and down alignment for top and bottom heater, heating for appointed local zone, prevents PCB to turn yellow.

IE-6200BGA/LED

Bottom heater up and down manually can adjust the heating height real time.

Adopt ceramics infrared radiator for IR heater, heating stably and uniformly with long serves life.

Human-machine interface has multiple operation mode and permission, soldering, desoldering and mounting manually, easy operation.

High resolution touch screen, which is up to 800*600 pixels.

Adopt joystick control for alignment system, no need setting complicated parameters.

Adopt Delta double ball bearing flow fan for air supply no need external air source.

Adopt DCCE 8 channel module for temperature control system, automatic PID adjustment.

Monitoring heaters real time, when accident happens, relevant sensors will send signal to PLC which will close output channel and display fault condition. Protect it self automatically.

Adopted 12" HD monitor

Model	IE-6200BGA Specification
Operation Mode	Automatic / Optical /Touch Panel
Voltage/Power	AC220V±10%(110V Optional), 50/60HZ / Top: 1200W, Bottom: 1200W, IR: 3200W
Heating Mode	Top/Bottom Nozzle Hot Air, Bottom Plates Infrared
Temperature Precision	2-3 °C (1 Sensor Port)
Preheat Zone	280×380mm
Optical Alignment Precision	0.01MM
CCD Magnification	5X~50X
LCD Display	17"1080P FHD LCD Display
For PCB Size/Chip Size	PCB Size: 415*370MM~6*6MM / Chip Size: 0.6*0.6~40*40MM
Machine Dimension	L640*W630*H920 (MM)
Net Weight	71KG
Standard Wooden Packing	Packing Size: L750*W700*H950 (MM) / G.W: 120KG

BGA REWORK STATION

IE-6800BGA

- Stable and Uniform Hot Air Heating System
- Lower Heater Adjustable
- Emergency Stop Function
- Lower Heater Adjustable
- Carbon Fiber Infrared Pre-heater
- External Air (N2) Supply Control System
- High-Precision PID Temperature Control System
- SMD Feeding Device Support (Optional)
- Industrial High-Definition CCD (2.0 MP)
- Automatic Placement, Desoldering
- Built-In Pressure Testing Device to Protects the PCB
- Real-Time Temperature Monitoring and Over-Temperature Protection
- Add a side camera, more clearly observe the rework process(Optional)
- High-Precision Optical Alignment System with Industrial High-Definition CCD (2MP)



FEATURES

The top heater can move freely along the X, Y axis in the IR preheating area. It is good for many BGA chips distribution at different positions in the PCB board which need repair. X-shaped infrared laser can do rapid location.

There are 3 independent heaters. The 1st and 2nd hot-air heaters can control multiple groups and segments temperature parameters. The 2nd heater can move up and down. The 3rd large area IR heater can preheat the PCB board fully to ensure no deformation to the board. Temperature, time, slope, cooling, alarming all can be displayed on the touch screen.

High-precision K-type thermocouple with close-loop control, PID auto-tuning system temperature system, combined with Panasonic PLC and highly sensitive temperature module for the precise temperature control, the temperature error controlled within $\pm 1^{\circ}$.

4V-groove PCB support, rapid positioning, convenience, accuracy, can fit for all kinds of PCB board. Flexible and removable universal fixture has protective effects and no damage to the PCB board, suitable for all kinds of BGA repair.

High-definition CCD color optical vision system, splitting, amplification, micro-adjust and auto-focus. With automatic color resolution and brightness adjustment device.

Without changing the magnification, the optical lens can be moved manually left and right, back and forth freely. It can observe all aspects of the BGA chip. It displays clearly. The X, Y axis and Z angle with micrometer adjust, precise positioning, alignment accuracy is within $\pm 0.01\text{mm}$, 15 TFT LCD Monitor. High automation, no human operations errors.

IE-6800BGA

CE certification, with emergency switch and automatic power-off protection device when emergency happens. With protective mesh to prevent components falling or human burns happen.

Mounting, welding and dewelding process are intelligent controlled and work automatically. BGA mounting position is controlled accurately. After finishing desoldering and soldering, there is alarming.

Powerful cross-flow fan to cool the PCB board automatically after desoldering and soldering, it can prevent the deformation of PCB board to ensure the welding effect.

With Multifunctional and humanized operation interface, there is "set up Interface" and "operation interface" on the touch screen to prevent wrong operations and setting. Temperature parameter has password protection to stop arbitrary changes.

This machine is equipped with pressure and optical sensors. To control the pressure in 3-10 gr and optical switches, so that it can automatically recognize the suction chip and mounting height, to ensure not crush BGA chip. It can repair Socket775 and double BGA / CGA / IC and various shielding devices, meet the requirement of lead-free process.

Model	IE-6200BGA Specification
Operation Mode	High Automatic / Optical / Laser / Touch Screen
Voltage/Power	AC 380V, 50/60HZ / Top:1000W, Bottom:1200W, IR: 4000W
Heating Mode	Top/Bottom Nozzle Hot Air, Bottom Plates Infrared
Preheating area size	L380mm×W500mm
Material	Servo Drive(Panasonic)+8" Touch Screen+PLC (Panasonic)
PCBA Positioning	Universal Fixture + Laser Positioning
Temperature Precision	±1°C, K-type thermocouple (Closed Loop, 6 Sensor Port)
Optical Alignment Precision	0.01MM
CCD Magnification:	5X~50X
For PCB Size/Chip Size	PCB Size: 560*470~10*10MM Chip Size: 1*1~80*80MM
Machine Dimension	L760*W850*H950(MM)
Net Weight	150KG
Standard Wooden Packing	Packing Size: L1150*W1250*H1350(MM)/ G.W: 205KG

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